



IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

Applicant: **Seutter, et al.**

Case: **5643/CALB/L/B**

Serial No.: **09/880,465**

Filed: **June 12, 2001**

Examiner: **Ha T. Nguyen**

Group Art Unit: **2812**

Title: **LOW-RESISTIVITY TUNGSTEN FROM HIGH-PRESSURE
CHEMICAL VAPOR DEPOSITION USING METAL-ORGANIC
PRECURSOR**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

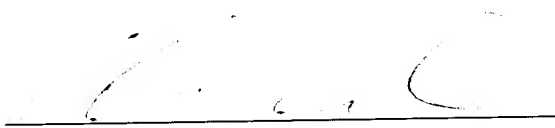
S I R:

SUBMISSION OF FORMAL DRAWINGS

The Applicants submit herewith 6 replacement sheets of formal drawings
(FIGS. 1 through 5B) in connection with the above-captioned application.

Respectfully submitted,

167323



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I hereby certify that this correspondence is being deposited on October 3, 2003 with the United States Postal Service as first-class mail, with sufficient postage, in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Stephen M. Liberty
Signature

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